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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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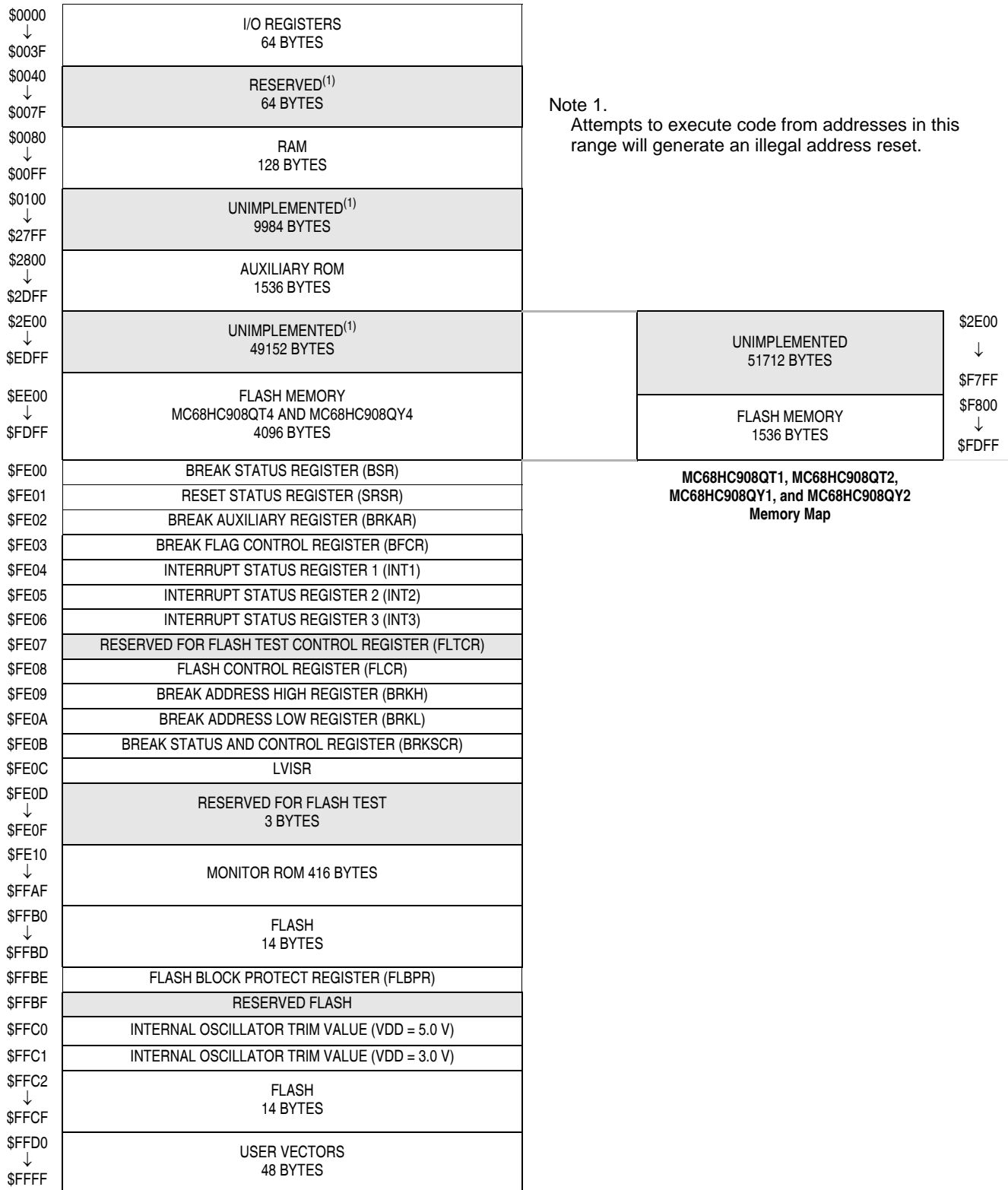
#### Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	5
Program Memory Size	1.5KB (1.5K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/nxp-semiconductors/mc68hc908qt1vpe">https://www.e-xfl.com/product-detail/nxp-semiconductors/mc68hc908qt1vpe</a>

## Revision History (Sheet 2 of 3)

Date	Revision Level	Description	Page Number(s)
August, 2003	1.0	Reformatted to meet latest M68HC08 documentation standards	N/A
		Figure 1-1. Block Diagram — Diagram redrawn to include keyboard interrupt module and TCLK pin designator.	20
		Figure 1-2. MCU Pin Assignments — Added TCLK pin designator.	21
		Table 1-2. Pin Functions — Added TCLK pin description.	22
		Table 1-3. Function Priority in Shared Pins — Revised table for clarity and to add TCLK.	23
		Figure 2-1. Memory Map — Corrected names for the IRQ status and control register (INTSCR) bits 3–0.	26
		3.7.3 ADC Input Clock Register — Clarified bit description for the ADC clock prescaler bits.	47
		4.3 Functional Description — Updated periodic wakeup request values.	51
		Figure 6-1. COP Block Diagram — Reworked for clarity	59
		Chapter 8 External Interrupt (IRQ) — Corrected bit names for MODE, IRQF, ACK, and IMASK	77–79
		Chapter 14 Timer Interface Module (TIM) — Added TCLK function.	131–139
		15.3 Monitor Module (MON) — Updated with additional data.	147
Chapter 16 Electrical Specifications — Updated with additional data.	169–173		
October, 2003	2.0	Figure 2-2. Control, Status, and Data Registers — Deleted unimplemented areas from \$FFB0–\$FFBD and \$FFC2–\$FFCF as they are actually available. Also corrected \$FFBF designation from unimplemented to reserved.	27
		Figure 6-1. COP Block Diagram — Reworked for clarity	59
		6.3.2 STOP Instruction — Added subsection	60
		13.4.2 Active Resets from Internal Sources — Reworked notes for clarity.	111
		Table 13-2. Reset Recovery Timing — Replaced previous table with new information.	112
		Chapter 14 Timer Interface Module (TIM) — Updated with additional data.	131
		Figure 15-3. Break I/O Register Summary — Corrected bit designators for the BRKAR register	143
		15.3 Monitor Module (MON) — Clarified seventh bullet.	147
Table 17-1. MC Order Numbers — Corrected temperature and package designators.	175		
January, 2004	3.0	Figure 2-2. Control, Status, and Data Registers — Corrected reset state for the FLASH Block Protect Register at address location \$FFBE and the Internal Oscillator Trim Value at \$FFC0.	32
		Figure 2-5. FLASH Block Protect Register (FLBPR) — Restated reset state for clarity.	38

## Memory



Note 1.  
Attempts to execute code from addresses in this range will generate an illegal address reset.

Figure 2-1. Memory Map

## 2.6 FLASH Memory (FLASH)

This subsection describes the operation of the embedded FLASH memory. The FLASH memory can be read, programmed, and erased from a single external supply. The program and erase operations are enabled through the use of an internal charge pump.

The FLASH memory consists of an array of 4096 or 1536 bytes with an additional 48 bytes for user vectors. The minimum size of FLASH memory that can be erased is 64 bytes; and the maximum size of FLASH memory that can be programmed in a program cycle is 32 bytes (a row). Program and erase operations are facilitated through control bits in the FLASH control register (FLCR). Details for these operations appear later in this section. The address ranges for the user memory and vectors are:

- \$EE00 – \$FDFF; user memory, 4096 bytes: MC68HC908QY4 and MC68HC908QT4
- \$F800 – \$FDFF; user memory, 1536 bytes: MC68HC908QY2, MC68HC908QT2, MC68HC908QY1 and MC68HC908QT1
- \$FFD0 – \$FFFF; user interrupt vectors, 48 bytes.

**NOTE**


*An erased bit reads as a 1 and a programmed bit reads as a 0.  
A security feature prevents viewing of the FLASH contents.<sup>(1)</sup>*

### 2.6.1 FLASH Control Register

The FLASH control register (FLCR) controls FLASH program and erase operations.

Address: \$FE08

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	HVEN	MASS	ERASE	PGM
Write:								
Reset:	0	0	0	0	0	0	0	0

 = Unimplemented

**Figure 2-3. FLASH Control Register (FLCR)**

#### HVEN — High Voltage Enable Bit

This read/write bit enables high voltage from the charge pump to the memory for either program or erase operation. It can only be set if either PGM = 1 or ERASE = 1 and the proper sequence for program or erase is followed.

- 1 = High voltage enabled to array and charge pump on
- 0 = High voltage disabled to array and charge pump off

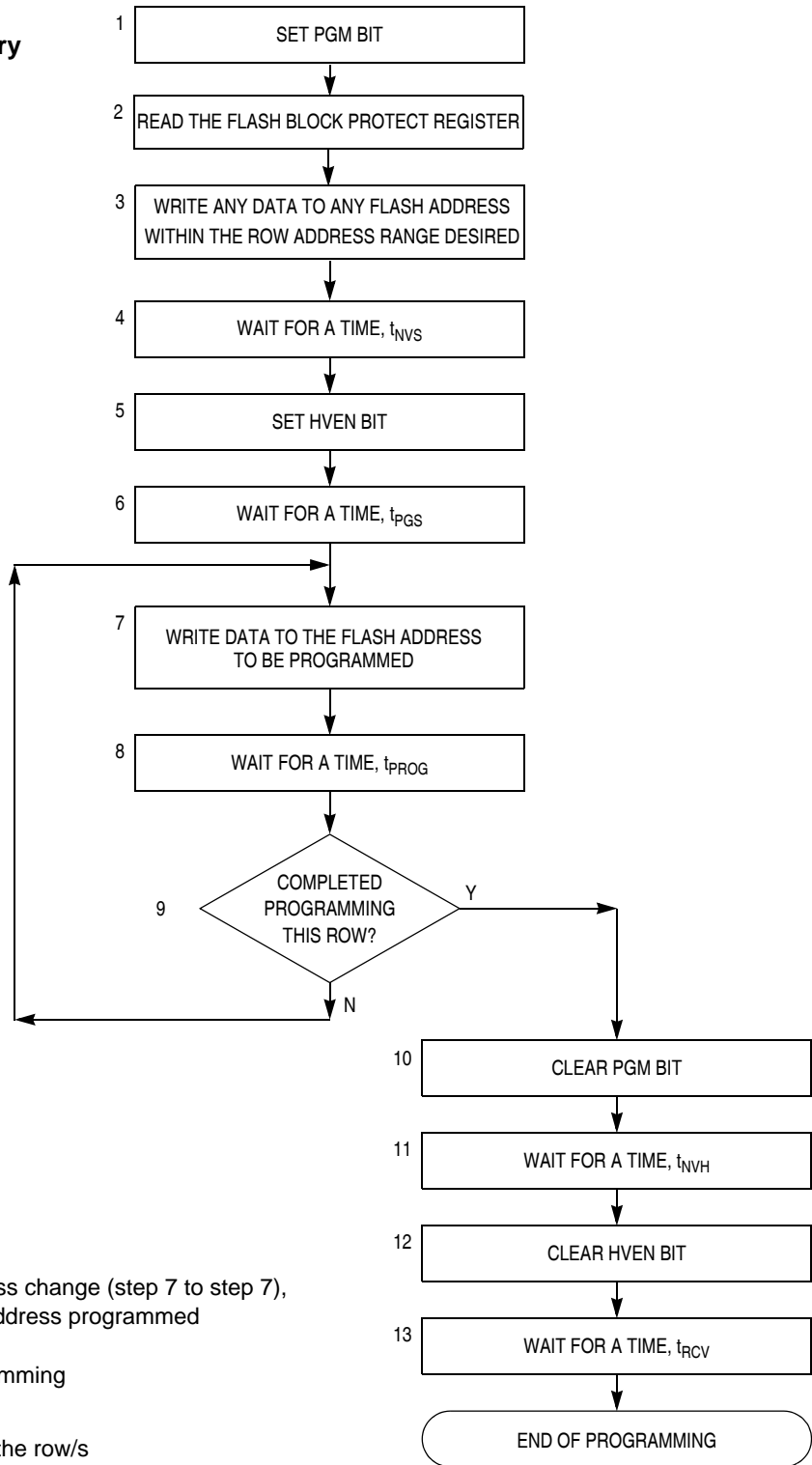
#### MASS — Mass Erase Control Bit

This read/write bit configures the memory for mass erase operation.

- 1 = Mass erase operation selected
- 0 = Mass erase operation unselected

1. No security feature is absolutely secure. However, Freescale's strategy is to make reading or copying the FLASH difficult for unauthorized users.

**Algorithm for Programming a Row (32 Bytes) of FLASH Memory**



**NOTES:**

The time between each FLASH address change (step 7 to step 7), or the time between the last FLASH address programmed to clearing PGM bit (step 7 to step 10) must not exceed the maximum programming time,  $t_{PROG\ max}$ .

This row program algorithm assumes the row/s to be programmed are initially erased.

**Figure 2-4. FLASH Programming Flowchart**

### 2.6.7 Wait Mode

Putting the MCU into wait mode while the FLASH is in read mode does not affect the operation of the FLASH memory directly, but there will not be any memory activity since the CPU is inactive.

The WAIT instruction should not be executed while performing a program or erase operation on the FLASH, or the operation will discontinue and the FLASH will be on standby mode.

### 2.6.8 Stop Mode

Putting the MCU into stop mode while the FLASH is in read mode does not affect the operation of the FLASH memory directly, but there will not be any memory activity since the CPU is inactive.

The STOP instruction should not be executed while performing a program or erase operation on the FLASH, or the operation will discontinue and the FLASH will be on standby mode

#### **NOTE**

*Standby mode is the power-saving mode of the FLASH module in which all internal control signals to the FLASH are inactive and the current consumption of the FLASH is at a minimum.*

## Configuration Register (CONFIG)

### IRQPUD — $\overline{\text{IRQ}}$ Pin Pullup Control Bit

- 1 = Internal pullup is disconnected
- 0 = Internal pullup is connected between  $\overline{\text{IRQ}}$  pin and  $V_{DD}$

### IRQEN — $\overline{\text{IRQ}}$ Pin Function Selection Bit

- 1 = Interrupt request function active in pin
- 0 = Interrupt request function inactive in pin

### OSCOPT1 and OSCOPT0 — Selection Bits for Oscillator Option

- (0, 0) Internal oscillator
- (0, 1) External oscillator
- (1, 0) External RC oscillator
- (1, 1) External XTAL oscillator

### RSTEN — $\overline{\text{RST}}$ Pin Function Selection

- 1 = Reset function active in pin
- 0 = Reset function inactive in pin

#### NOTE

The RSTEN bit is cleared by a power-on reset (POR) only. Other resets will leave this bit unaffected.

Address: \$001F

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVI5OR3	SSREC	STOP	COPD
Write:								
Reset:	0	0	0	0	U	0	0	0
POR:	0	0	0	0	0	0	0	0

U = Unaffected

**Figure 5-2. Configuration Register 1 (CONFIG1)**

### COPRS (Out of STOP Mode) — COP Reset Period Selection Bit

- 1 = COP reset short cycle =  $8176 \times \text{BUSCLKX4}$
- 0 = COP reset long cycle =  $262,128 \times \text{BUSCLKX4}$

### COPRS (In STOP Mode) — Auto Wakeup Period Selection Bit

- 1 = Auto wakeup short cycle =  $512 \times \text{INTRCOSC}$
- 0 = Auto wakeup long cycle =  $16,384 \times \text{INTRCOSC}$

### LVISTOP — LVI Enable in Stop Mode Bit

When the LVIPWRD bit is clear, setting the LVISTOP bit enables the LVI to operate during stop mode. Reset clears LVISTOP.

- 1 = LVI enabled during stop mode
- 0 = LVI disabled during stop mode

### LVIRSTD — LVI Reset Disable Bit

LVIRSTD disables the reset signal from the LVI module.

- 1 = LVI module resets disabled
- 0 = LVI module resets enabled

Table 7-1. Instruction Set Summary (Sheet 3 of 6)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles	
			V	H	I	N	Z					C
CLI	Clear Interrupt Mask	$I \leftarrow 0$	-	-	0	-	-	-	INH	9A		2
CLR <i>opr</i> CLRA CLR $X$ CLR $H$ CLR <i>opr,X</i> CLR $,X$ CLR <i>opr,SP</i>	Clear	$M \leftarrow \$00$ $A \leftarrow \$00$ $X \leftarrow \$00$ $H \leftarrow \$00$ $M \leftarrow \$00$ $M \leftarrow \$00$ $M \leftarrow \$00$	0	-	-	0	1	-	DIR INH INH INH IX1 IX SP1	3F 4F 5F 8C 6F 7F 9E6F	dd  ff ff	3 1 1 1 3 2 4
CMP # <i>opr</i> CMP <i>opr</i> CMP <i>opr</i> CMP <i>opr,X</i> CMP <i>opr,X</i> CMP $,X$ CMP <i>opr,SP</i> CMP <i>opr,SP</i>	Compare A with M	$(A) - (M)$	†	-	-	†	†	†	IMM DIR EXT IX2 IX1 IX SP1 SP2	A1 B1 C1 D1 E1 F1 9EE1 9ED1	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
COM <i>opr</i> COMA COM $X$ COM <i>opr,X</i> COM $,X$ COM <i>opr,SP</i>	Complement (One's Complement)	$M \leftarrow (\overline{M}) = \$FF - (M)$ $A \leftarrow (\overline{A}) = \$FF - (M)$ $X \leftarrow (\overline{X}) = \$FF - (M)$ $M \leftarrow (\overline{M}) = \$FF - (M)$ $M \leftarrow (\overline{M}) = \$FF - (M)$ $M \leftarrow (\overline{M}) = \$FF - (M)$	0	-	-	†	†	1	DIR INH INH IX1 IX SP1	33 43 53 63 73 9E63	dd  ff ff ff	4 1 1 4 3 5
CPHX # <i>opr</i> CPHX <i>opr</i>	Compare H:X with M	$(H:X) - (M:M + 1)$	†	-	-	†	†	†	IMM DIR	65 75	ii ii+1 dd	3 4
CPX # <i>opr</i> CPX <i>opr</i> CPX <i>opr</i> CPX $,X$ CPX <i>opr,X</i> CPX <i>opr,X</i> CPX <i>opr,SP</i> CPX <i>opr,SP</i>	Compare X with M	$(X) - (M)$	†	-	-	†	†	†	IMM DIR EXT IX2 IX1 IX SP1 SP2	A3 B3 C3 D3 E3 F3 9EE3 9ED3	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
DAA	Decimal Adjust A	$(A)_{10}$	U	-	-	†	†	†	INH	72		2
DBNZ <i>opr,rel</i> DBNZ $A,rel$ DBNZ $X,rel$ DBNZ <i>opr,X,rel</i> DBNZ $X,rel$ DBNZ <i>opr,SP,rel</i>	Decrement and Branch if Not Zero	$A \leftarrow (A) - 1$ or $M \leftarrow (M) - 1$ or $X \leftarrow (X) - 1$ $PC \leftarrow (PC) + 3 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 2 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 2 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 3 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 2 + rel ? (result) \neq 0$ $PC \leftarrow (PC) + 4 + rel ? (result) \neq 0$	-	-	-	-	-	-	DIR INH INH IX1 IX SP1	3B 4B 5B 6B 7B 9E6B	dd rr rr rr ff rr rr ff rr	5 3 3 5 4 6
DEC <i>opr</i> DECA DEC $X$ DEC <i>opr,X</i> DEC $,X$ DEC <i>opr,SP</i>	Decrement	$M \leftarrow (M) - 1$ $A \leftarrow (A) - 1$ $X \leftarrow (X) - 1$ $M \leftarrow (M) - 1$ $M \leftarrow (M) - 1$ $M \leftarrow (M) - 1$	†	-	-	†	†	-	DIR INH INH IX1 IX SP1	3A 4A 5A 6A 7A 9E6A	dd  ff ff	4 1 1 4 3 5
DIV	Divide	$A \leftarrow (H:A)/(X)$ $H \leftarrow \text{Remainder}$	-	-	-	-	†	†	INH	52		7
EOR # <i>opr</i> EOR <i>opr</i> EOR <i>opr</i> EOR <i>opr,X</i> EOR <i>opr,X</i> EOR $,X$ EOR <i>opr,SP</i> EOR <i>opr,SP</i>	Exclusive OR M with A	$A \leftarrow (A \oplus M)$	0	-	-	†	†	-	IMM DIR EXT IX2 IX1 IX SP1 SP2	A8 B8 C8 D8 E8 F8 9EE8 9ED8	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
INC <i>opr</i> INCA INC $X$ INC <i>opr,X</i> INC $,X$ INC <i>opr,SP</i>	Increment	$M \leftarrow (M) + 1$ $A \leftarrow (A) + 1$ $X \leftarrow (X) + 1$ $M \leftarrow (M) + 1$ $M \leftarrow (M) + 1$ $M \leftarrow (M) + 1$	†	-	-	†	†	-	DIR INH INH IX1 IX SP1	3C 4C 5C 6C 7C 9E6C	dd  ff ff	4 1 1 4 3 5



# Chapter 9

## Keyboard Interrupt Module (KBI)

### 9.1 Introduction

The keyboard interrupt module (KBI) provides six independently maskable external interrupts, which are accessible via the PTA0–PTA5 pins.

### 9.2 Features

Features of the keyboard interrupt module include:

- Six keyboard interrupt pins with separate keyboard interrupt enable bits and one keyboard interrupt mask
- Software configurable pullup device if input pin is configured as input port bit
- Programmable edge-only or edge and level interrupt sensitivity
- Exit from low-power modes

### 9.3 Functional Description

The keyboard interrupt module controls the enabling/disabling of interrupt functions on the six port A pins. These six pins can be enabled/disabled independently of each other. Refer to [Figure 9-2](#).

#### 9.3.1 Keyboard Operation

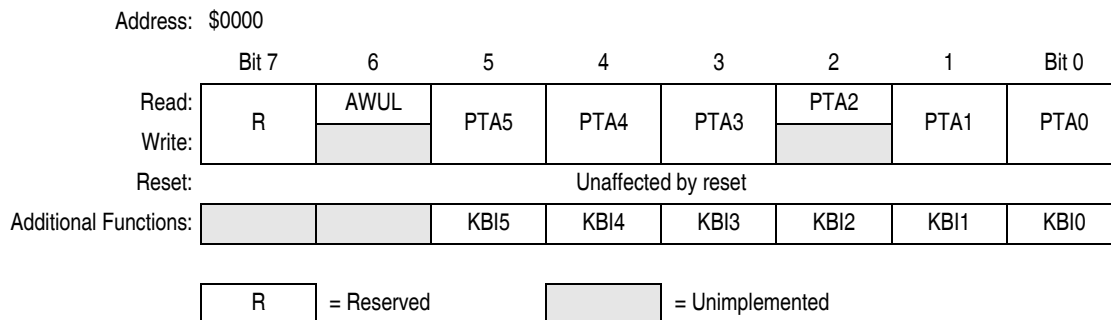
Writing to the KBIE0–KBIE5 bits in the keyboard interrupt enable register (KBIER) independently enables or disables each port A pin as a keyboard interrupt pin. Enabling a keyboard interrupt pin in port A also enables its internal pullup device irrespective of PTAPUE<sub>x</sub> bits in the port A input pullup enable register (see [12.2.3 Port A Input Pullup Enable Register](#)). A logic 0 applied to an enabled keyboard interrupt pin latches a keyboard interrupt request.

A keyboard interrupt is latched when one or more keyboard interrupt inputs goes low after all were high. The MODEK bit in the keyboard status and control register controls the triggering mode of the keyboard interrupt.

- If the keyboard interrupt is edge-sensitive only, a falling edge on a keyboard interrupt input does not latch an interrupt request if another keyboard pin is already low. To prevent losing an interrupt request on one input because another input is still low, software can disable the latter input while it is low.
- If the keyboard interrupt is falling edge and low-level sensitive, an interrupt request is present as long as any keyboard interrupt input is low.

### 12.2.1 Port A Data Register

The port A data register (PTA) contains a data latch for each of the six port A pins.



**Figure 12-1. Port A Data Register (PTA)**

#### PTA[5:0] — Port A Data Bits

These read/write bits are software programmable. Data direction of each port A pin is under the control of the corresponding bit in data direction register A. Reset has no effect on port A data.

#### AWUL — Auto Wakeup Latch Data Bit

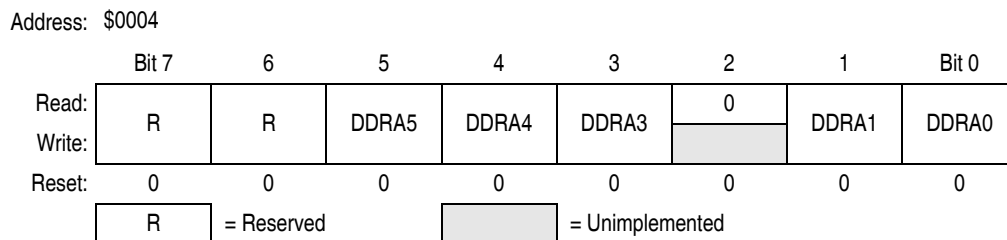
This is a read-only bit which has the value of the auto wakeup interrupt request latch. The wakeup request signal is generated internally (see [Chapter 4 Auto Wakeup Module \(AWU\)](#)). There is no PTA6 port nor any of the associated bits such as PTA6 data register, pullup enable or direction.

#### KBI[5:0] — Port A Keyboard Interrupts

The keyboard interrupt enable bits, KBIE5–KBIE0, in the keyboard interrupt control enable register (KBIER) enable the port A pins as external interrupt pins (see [Chapter 9 Keyboard Interrupt Module \(KBI\)](#)).

### 12.2.2 Data Direction Register A

Data direction register A (DDRA) determines whether each port A pin is an input or an output. Writing a 1 to a DDRA bit enables the output buffer for the corresponding port A pin; a 0 disables the output buffer.



**Figure 12-2. Data Direction Register A (DDRA)**

#### DDRA[5:0] — Data Direction Register A Bits

These read/write bits control port A data direction. Reset clears DDRA[5:0], configuring all port A pins as inputs.

- 1 = Corresponding port A pin configured as output
- 0 = Corresponding port A pin configured as input

**NOTE**

*Avoid glitches on port A pins by writing to the port A data register before changing data direction register A bits from 0 to 1.*

Figure 12-3 shows the port A I/O logic.

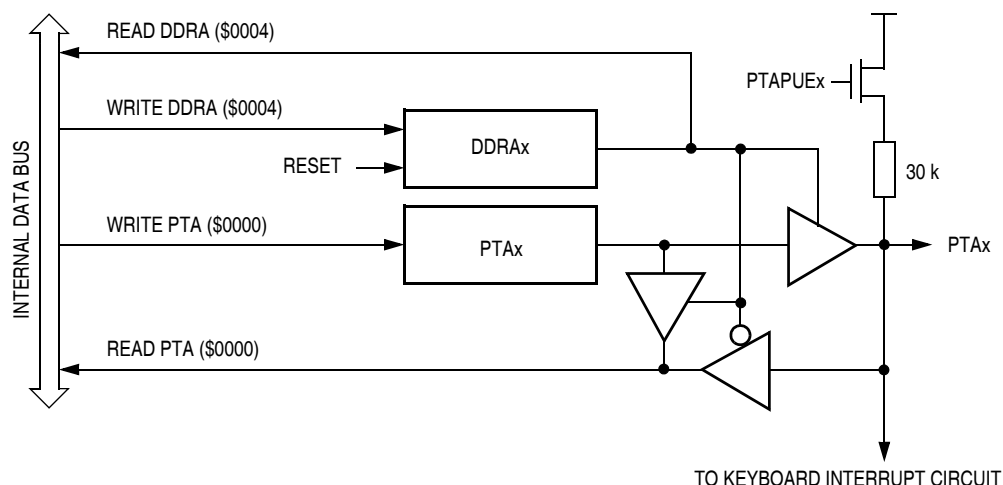


Figure 12-3. Port A I/O Circuit

**NOTE**

Figure 12-3 does not apply to PTA2

When DDRAx is a 1, reading address \$0000 reads the PTAx data latch. When DDRAx is a 0, reading address \$0000 reads the voltage level on the pin. The data latch can always be written, regardless of the state of its data direction bit.

**12.2.3 Port A Input Pullup Enable Register**

The port A input pullup enable register (PTAPUE) contains a software configurable pullup device for each of the six port A pins. Each bit is individually configurable and requires the corresponding data direction register, DDRAx, to be configured as input. Each pullup device is automatically and dynamically disabled when its corresponding DDRAx bit is configured as output.

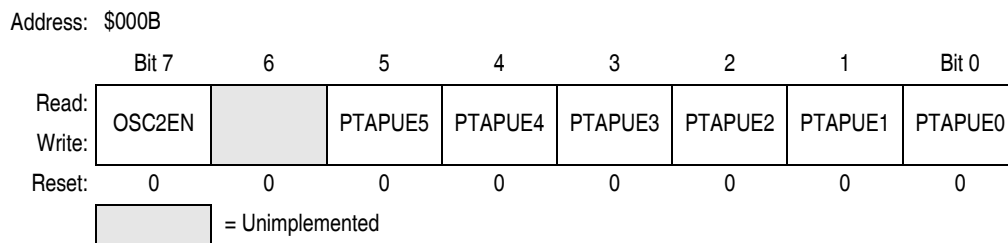


Figure 12-4. Port A Input Pullup Enable Register (PTAPUE)

**OSC2EN — Enable PTA4 on OSC2 Pin**

This read/write bit configures the OSC2 pin function when internal oscillator or RC oscillator option is selected. This bit has no effect for the XTAL or external oscillator options.

1 = OSC2 pin outputs the internal or RC oscillator clock (BUSCLKX4)

0 = OSC2 pin configured for PTA4 I/O, having all the interrupt and pullup functions

### 13.5.2 SIM Counter During Stop Mode Recovery

The SIM counter also is used for stop mode recovery. The STOP instruction clears the SIM counter. After an interrupt, break, or reset, the SIM senses the state of the short stop recovery bit, SSREC, in the configuration register 1 (CONFIG1). If the SSREC bit is a 1, then the stop recovery is reduced from the normal delay of 4096 BUSCLKX4 cycles down to 32 BUSCLKX4 cycles. This is ideal for applications using canned oscillators that do not require long start-up times from stop mode. External crystal applications should use the full stop recovery time, that is, with SSREC cleared in the configuration register 1 (CONFIG1).

### 13.5.3 SIM Counter and Reset States

External reset has no effect on the SIM counter (see [13.7.2 Stop Mode](#) for details.) The SIM counter is free-running after all reset states. See [13.4.2 Active Resets from Internal Sources](#) for counter control and internal reset recovery sequences.

## 13.6 Exception Control

Normal sequential program execution can be changed in three different ways:

1. Interrupts
  - a. Maskable hardware CPU interrupts
  - b. Non-maskable software interrupt instruction (SWI)
2. Reset
3. Break interrupts

### 13.6.1 Interrupts

An interrupt temporarily changes the sequence of program execution to respond to a particular event. [Figure 13-7](#) flow charts the handling of system interrupts.

Interrupts are latched, and arbitration is performed in the SIM at the start of interrupt processing. The arbitration result is a constant that the CPU uses to determine which vector to fetch. Once an interrupt is latched by the SIM, no other interrupt can take precedence, regardless of priority, until the latched interrupt is serviced (or the I bit is cleared).

At the beginning of an interrupt, the CPU saves the CPU register contents on the stack and sets the interrupt mask (I bit) to prevent additional interrupts. At the end of an interrupt, the RTI instruction recovers the CPU register contents from the stack so that normal processing can resume. [Figure 13-8](#) shows interrupt entry timing. [Figure 13-9](#) shows interrupt recovery timing.

### 13.6.2.1 Interrupt Status Register 1

Address: \$FE04

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	IF5	IF4	IF3	0	IF1	0	0
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

**Figure 13-11. Interrupt Status Register 1 (INT1)**

#### IF1 and IF3–IF5 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in [Table 13-3](#).

1 = Interrupt request present

0 = No interrupt request present

#### Bit 0, 1, 3, and 7 — Always read 0

### 13.6.2.2 Interrupt Status Register 2

Address: \$FE05

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF14	0	0	0	0	0	0	0
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

**Figure 13-12. Interrupt Status Register 2 (INT2)**

#### IF14 — Interrupt Flags

This flag indicates the presence of interrupt requests from the sources shown in [Table 13-3](#).

1 = Interrupt request present

0 = No interrupt request present

#### Bit 0–6 — Always read 0

### 13.6.2.3 Interrupt Status Register 3

Address: \$FE06

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	0	0	0	IF15
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

**Figure 13-13. Interrupt Status Register 3 (INT3)**

#### IF15 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in [Table 13-3](#).

1 = Interrupt request present

0 = No interrupt request present

#### Bit 1–7 — Always read 0

control the output are the ones written to last. TSC0 controls and monitors the buffered output compare function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

**NOTE**

*In buffered output compare operation, do not write new output compare values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered output compares.*

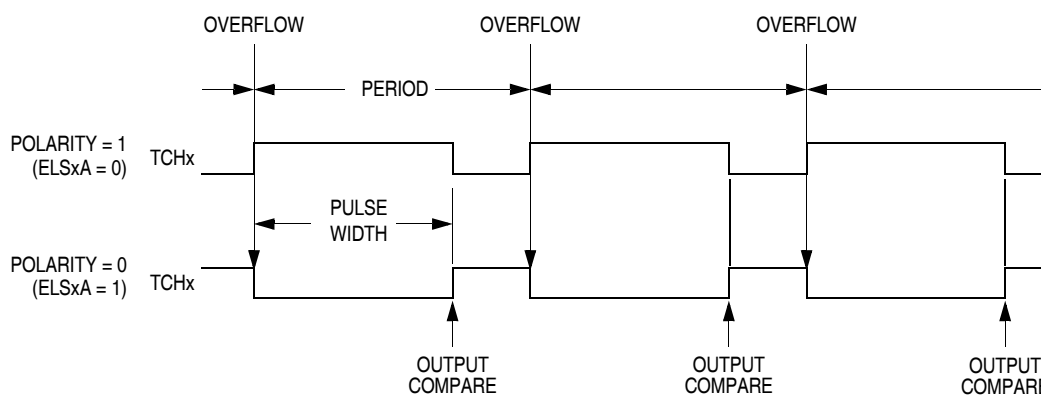
**14.4.4 Pulse Width Modulation (PWM)**

By using the toggle-on-overflow feature with an output compare channel, the TIM can generate a PWM signal. The value in the TIM counter modulo registers determines the period of the PWM signal. The channel pin toggles when the counter reaches the value in the TIM counter modulo registers. The time between overflows is the period of the PWM signal

As [Figure 14-3](#) shows, the output compare value in the TIM channel registers determines the pulse width of the PWM signal. The time between overflow and output compare is the pulse width. Program the TIM to clear the channel pin on output compare if the state of the PWM pulse is logic 1 (ELSxA = 0). Program the TIM to set the pin if the state of the PWM pulse is logic 0 (ELSxA = 1).

The value in the TIM counter modulo registers and the selected prescaler output determines the frequency of the PWM output. The frequency of an 8-bit PWM signal is variable in 256 increments. Writing \$00FF (255) to the TIM counter modulo registers produces a PWM period of 256 times the internal bus clock period if the prescaler select value is 000. See [14.9.1 TIM Status and Control Register](#).

The value in the TIM channel registers determines the pulse width of the PWM output. The pulse width of an 8-bit PWM signal is variable in 256 increments. Writing \$0080 (128) to the TIM channel registers produces a duty cycle of 128/256 or 50%.



**Figure 14-3. PWM Period and Pulse Width**

### 15.3.2 Security

A security feature discourages unauthorized reading of FLASH locations while in monitor mode. The host can bypass the security feature at monitor mode entry by sending eight security bytes that match the bytes at locations \$FFF6–\$FFFD. Locations \$FFF6–\$FFFD contain user-defined data.

**NOTE**

*Do not leave locations \$FFF6–\$FFFD blank. For security reasons, program locations \$FFF6–\$FFFD even if they are not used for vectors.*

During monitor mode entry, the MCU waits after the power-on reset for the host to send the eight security bytes on pin PTA0. If the received bytes match those at locations \$FFF6–\$FFFD, the host bypasses the security feature and can read all FLASH locations and execute code from FLASH. Security remains bypassed until a power-on reset occurs. If the reset was not a power-on reset, security remains bypassed and security code entry is not required. See [Figure 15-18](#).

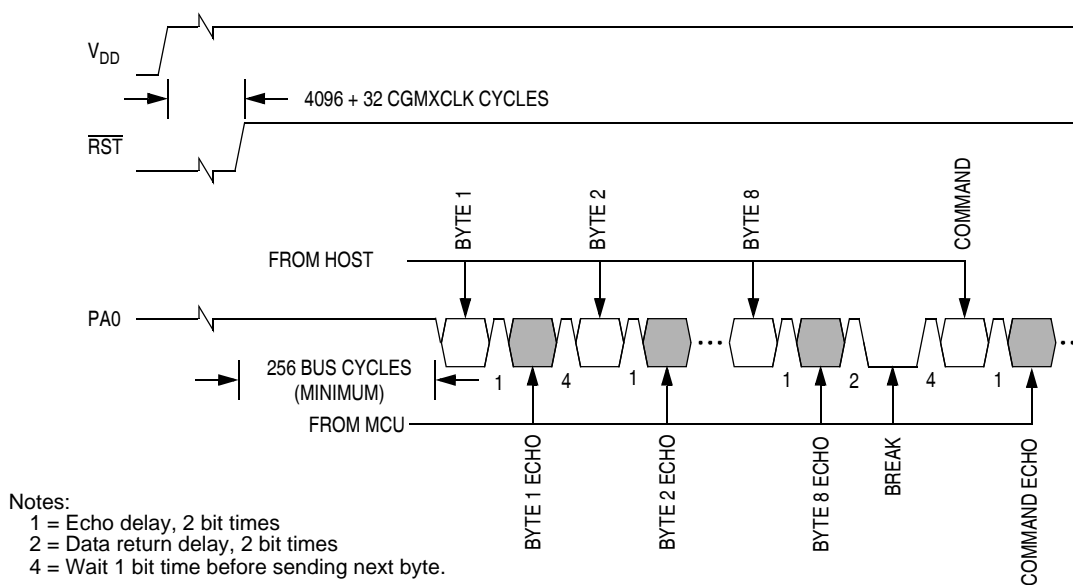
Upon power-on reset, if the received bytes of the security code do not match the data at locations \$FFF6–\$FFFD, the host fails to bypass the security feature. The MCU remains in monitor mode, but reading a FLASH location returns an invalid value and trying to execute code from FLASH causes an illegal address reset. After receiving the eight security bytes from the host, the MCU transmits a break character, signifying that it is ready to receive a command.

**NOTE**

*The MCU does not transmit a break character until after the host sends the eight security bytes.*

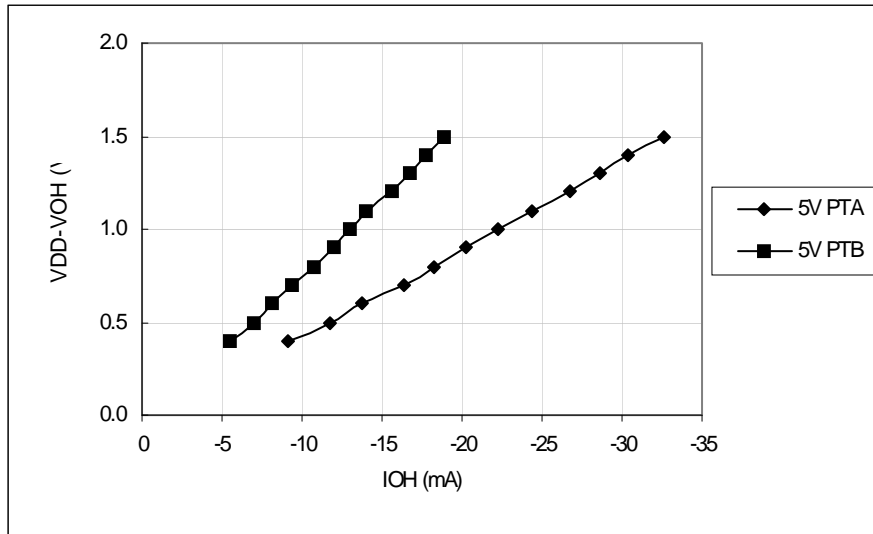
To determine whether the security code entered is correct, check to see if bit 6 of RAM address \$80 is set. If it is, then the correct security code has been entered and FLASH can be accessed.

If the security sequence fails, the device should be reset by a power-on reset and brought up in monitor mode to attempt another entry. After failing the security sequence, the FLASH module can also be mass erased by executing an erase routine that was downloaded into internal RAM. The mass erase operation clears the security code locations so that all eight security bytes become \$FF (blank).

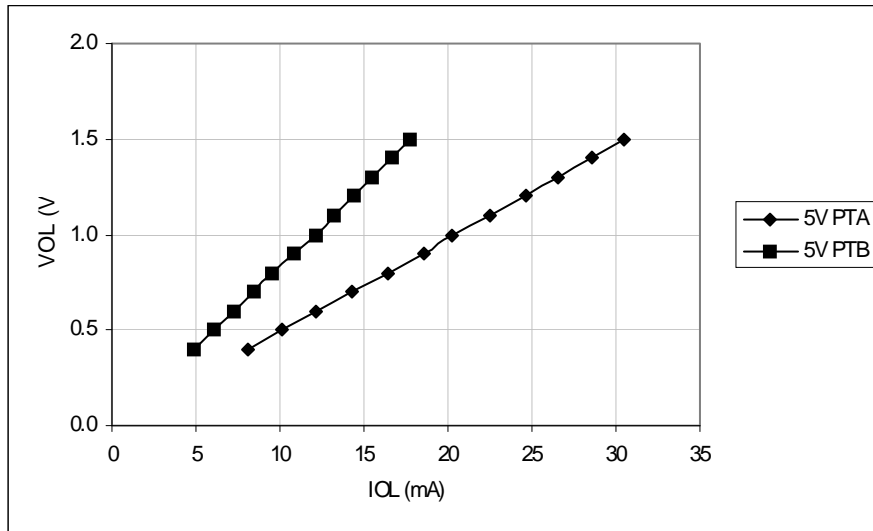


**Figure 15-18. Monitor Mode Entry Timing**

## 16.6 Typical 5-V Output Drive Characteristics



**Figure 16-1. Typical 5-Volt Output High Voltage versus Output High Current (25°C)**



**Figure 16-2. Typical 5-Volt Output Low Voltage versus Output Low Current (25°C)**



### 16.11 3-V Control Timing

Characteristic <sup>(1)</sup>	Symbol	Min	Max	Unit
Internal operating frequency	$f_{OP}$ ( $f_{Bus}$ )	—	4	MHz
Internal clock period ( $1/f_{OP}$ )	$t_{cyc}$	250	—	ns
$\overline{RST}$ input pulse width low	$t_{RL}$	200	—	ns
$\overline{IRQ}$ interrupt pulse width low (edge-triggered)	$t_{LIH}$	200	—	ns
$\overline{IRQ}$ interrupt pulse period	$t_{LIL}$	Note <sup>(2)</sup>	—	$t_{cyc}$

- $V_{DD} = 2.7$  to  $3.3$  Vdc,  $V_{SS} = 0$  Vdc,  $T_A = T_L$  to  $T_H$ ; timing shown with respect to 20%  $V_{DD}$  and 70%  $V_{DD}$ , unless otherwise noted.
- The minimum period is the number of cycles it takes to execute the interrupt service routine plus 1  $t_{cyc}$ .

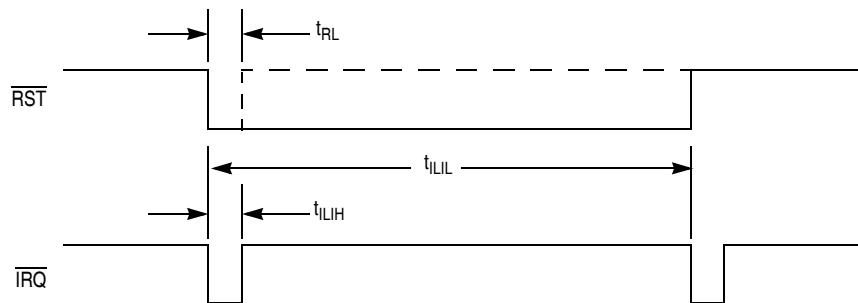


Figure 16-7.  $\overline{RST}$  and  $\overline{IRQ}$  Timing



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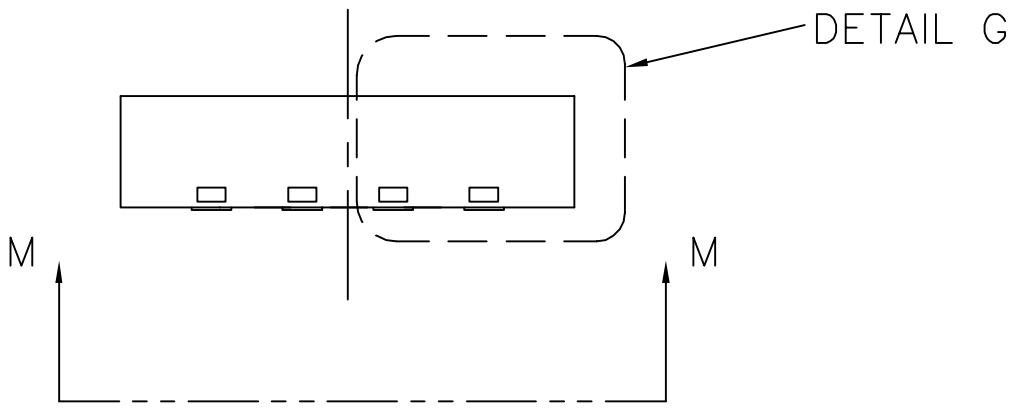
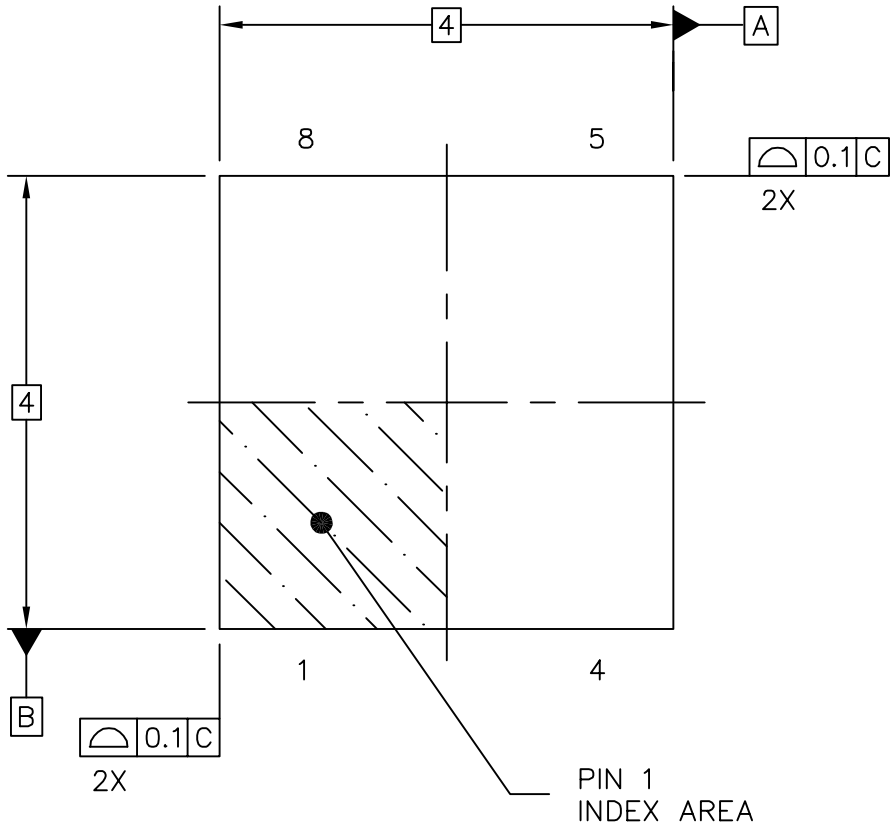
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DOCUMENT NO: 98ARL10557D

PAGE: 1452

DO NOT SCALE THIS DRAWING

REV: A



TITLE: THERMALLY ENHANCED DUAL  
 FLAT NO LEAD PACKAGE (DFN)  
 8 TERMINAL, 0.8 PITCH (4 X 4 X 1)

CASE NUMBER: 1452-01

STANDARD: NON-JEDEC

PACKAGE CODE: 6165

SHEET: 1 OF 5



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PAGE: 751G

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REV: E

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS A AND B TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
5. THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.62 mm.

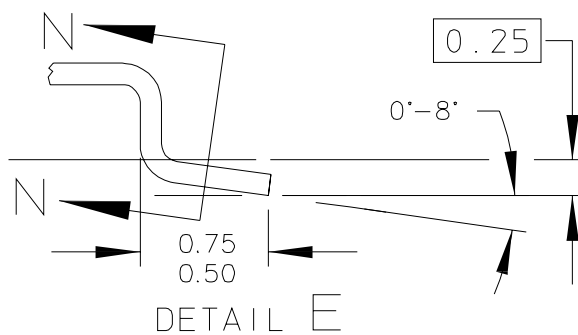
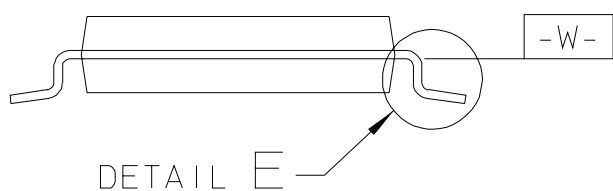
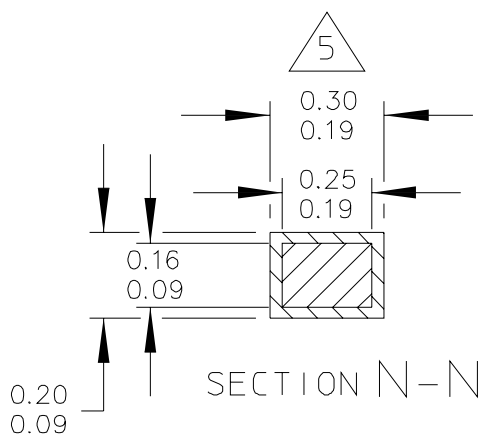
TITLE:  
 16LD SOIC W/B, 1.27 PITCH,  
 CASE OUTLINE

CASE NUMBER: 751G-05

STANDARD: JEDEC MS-013AA

PACKAGE CODE: 2003

SHEET: 2 OF 3



TITLE:

16 LD TSSOP, PITCH 0.65MM

CASE NUMBER: 948F-01

STANDARD: JEDEC

PACKAGE CODE: 6117

SHEET: 2 OF 4

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